

## General Description

The Sanrise SRC60R075BS is a high voltage power MOSFET, fabricated using advanced super junction technology. The resulting device has extremely low on resistance, low gate charge and fast switching time, making it especially suitable for applications which require superior power density and outstanding efficiency.

The SRC60R075BS break down voltage is 600V and it has a high rugged avalanche characteristics. The SRC60R075BS is available in PDFN8\*8 package.

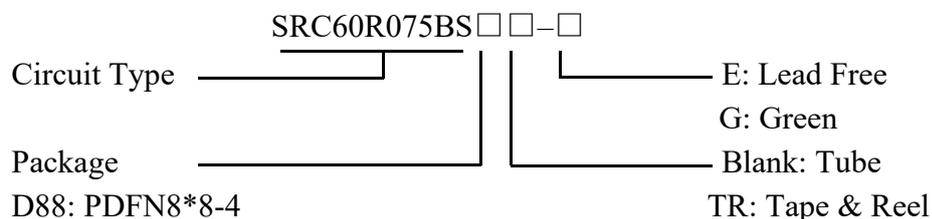
## Features

- Ultra Low  $R_{DS(ON)} = 75m\Omega @ V_{GS} = 10V$ .
- Ultra Low Gate Charge,  $Q_g = 110nC$  typ.
- Fast switching capability
- Robust design with better EAS performance
- EMI Improved
- Non-automotive Qualified

## Application

- Telecom Power
- EV Charger
- High Power Application

## Ordering Information



## Symbol

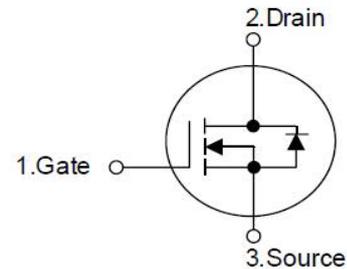
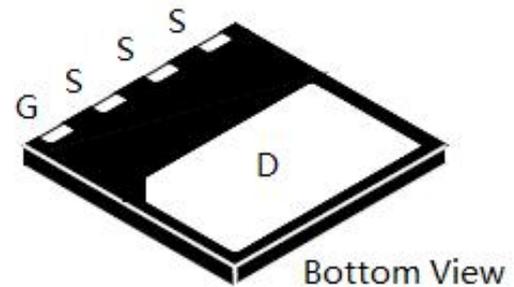


Figure 1 Symbol of SRC60R075BS

## Package Type



PDFN8\*8-4

Figure 2 Package Type of SRC60R075BS

Package	Part Number	Marking ID	Packing Type
PDFN8*8-4	SRC60R075BSD88TR-G	SRC60R075BSD88G	Tape & Reel

**Absolute Maximum Ratings**<sup>Note 1</sup>

Parameter		Symbol	Rating	Unit
Drain-Source Voltage		$V_{DSS}$	600	V
Gate-Source Voltage (static)		$V_{GSS}$	±20	V
Gate-Source Voltage (dynamic), AC ( $f > 1$ Hz)		$V_{GSS}$	±30	V
Power Dissipation ( $T_C=25^\circ\text{C}$ , PDFN8*8-4)		$P_{tot}$	357.1	W
Continuous Drain Current	$T_C=25^\circ\text{C}$	$I_D$	48	A
	$T_C=100^\circ\text{C}$		30.3	
	$T_C=125^\circ\text{C}$		21.5	
Pulsed Drain Current (Note 2)		$I_{DM}$	144	A
Avalanche Energy, Single Pulse (Note 3)		$E_{AS}$	125	mJ
Avalanche Energy, Repetitive (Note 2)		$E_{AR}$	0.6	mJ
Avalanche Current, Repetitive (Note 2)		$I_{AR}$	5.0	A
Continuous Diode Forward Current		$I_S$	48	A
Diode Pulse Current		$I_{S,PULSE}$	144	A
MOSFET dv/dt Ruggedness, $V_{DS} \leq 480\text{V}$		dv/dt	80	V/ns
Reverse Diode dv/dt, $V_{DS} \leq 480\text{V}$ , $I_{SD} \leq I_D$		dv/dt	50	V/ns
Power Dissipation ( $T_C=25^\circ\text{C}$ )		$P_{tot}$	357	W
Operating Junction Temperature		$T_J$	150	°C
Storage Temperature		$T_{STG}$	-55 to 150	°C
Lead Temperature (Soldering, 10 sec)		$T_{LEAD}$	260	°C

Note:

- Absolute maximum ratings are those values beyond which the device could be permanently damaged. Absolute maximum ratings are stress ratings only and functional device operation is not implied.
- Repetitive Rating: Pulse width limited by maximum junction temperature
- $I_{AS} = 5\text{A}$ ,  $V_{DD} = 60\text{V}$ ,  $R_G = 25\Omega$ , Starting  $T_J = 25^\circ\text{C}$

**Thermal characteristics**

Parameter		Symbol	Min	Typ	Max	Unit
Thermal resistance, Junction-to-Case	PDFN8*8-4	$R_{thJC}$			0.35	°C/W
Thermal resistance, Junction-to-Ambient	PDFN8*8-4	$R_{thJA}$			58	°C/W

## Electrical Characteristics

$T_J = 25^\circ\text{C}$ , unless otherwise specified.

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
<b>Statistic Characteristics</b>						
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS}=0V, I_D=250\mu A$	600			V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS}=600V, V_{GS}=0V$			10	$\mu A$
Gate-Body Leakage Current	Forward	$I_{GSSF}, V_{GS}=30V, V_{DS}=0V$			100	nA
	Reverse	$I_{GSSR}, V_{GS}=-30V, V_{DS}=0V$			-100	
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{DS}=V_{GS}, I_D=5.0mA$	3.7	4.3	5.3	V
Static Drain-Source On-Resistance	$R_{DS(ON)}$	$V_{GS}=10V, I_D=24A$		65	75	mΩ
Gate Resistance	$R_G$	f=1MHz, Open Drain	0.11	0.55	5.0	Ω
<b>Dynamic Characteristics</b>						
Input Capacitance	$C_{ISS}$	$V_{DS}=25V, V_{GS}=0V, f=1MHz$	2.6	4.32	6.6	nF
Output Capacitance	$C_{OSS}$		1	2.8	8	nF
Reverse Transfer Capacitance	$C_{RSS}$		10	33	300	pF
Effective output capacitance, energy related <sup>NOTE5</sup>	$C_{O(er)}$	$V_{GS}=0V, V_{DS}=0\dots 400V$		94		pF
Effective output capacitance, time related <sup>NOTE6</sup>	$C_{O(tr)}$			550		
Turn-on Delay Time	$t_{d(on)}$	$V_{DD}=400V, I_D=24A, R_G=3.3\Omega, V_{GS}=10V$		16		ns
Rise Time	$t_r$			6.0		
Turn-off Delay Time	$t_{d(off)}$			98		
Fall Time	$t_f$			4.0		
<b>Gate Charge Characteristics</b>						
Gate to Source Charge	$Q_{gs}$	$V_{DD}=480V, I_D=24A, V_{GS}=0 \text{ to } 10V$		28.1		nC
Gate to Drain Charge	$Q_{gd}$			56.0		
Gate Charge Total	$Q_g$			110	160	
Gate Plateau Voltage	$V_{plateau}$			6.5		V
<b>Reverse Diode Characteristics</b>						
Drain-Source Diode Forward Voltage	$V_{SD}$	$V_{GS}=0V, I_{SD}=24A$		0.9	1.1	V
Reverse Recovery Time	$t_{rr}$	$V_R=400V, I_F=24A, dI_F/dt=100A/\mu s$		141	200	ns
Reverse Recovery Charge	$Q_{rr}$			0.83	1.66	$\mu C$
Peak Reverse Recovery Current	$I_{rrm}$			11.8		A

Note:

- $C_{O(er)}$  is a fixed capacitance that gives the same stored energy as  $C_{OSS}$  while  $V_{DS}$  is rising from 0 to 480V
- $C_{O(tr)}$  is a fixed capacitance that gives the same charging time as  $C_{OSS}$  while  $V_{DS}$  is rising from 0 to 480V



Shenzhen Sanrise Technology Co., LTD

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